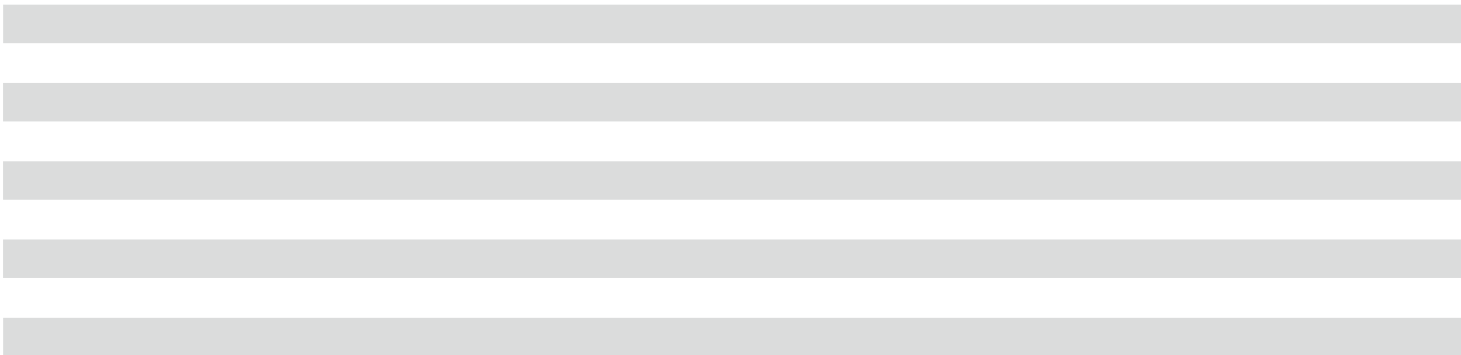
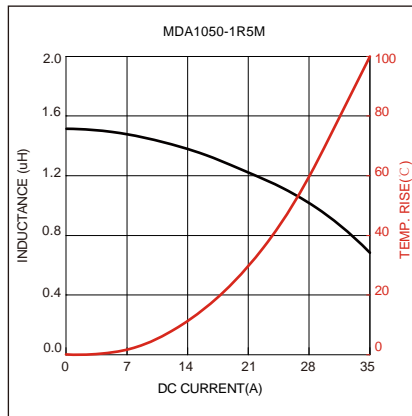
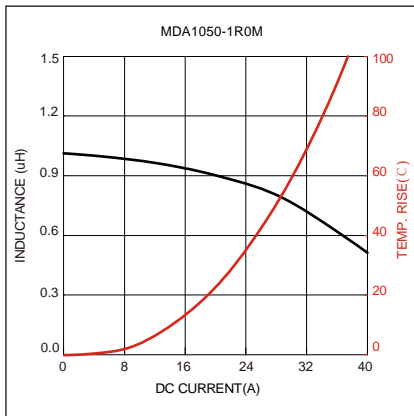
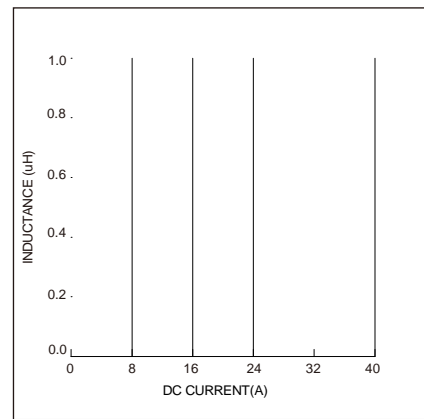
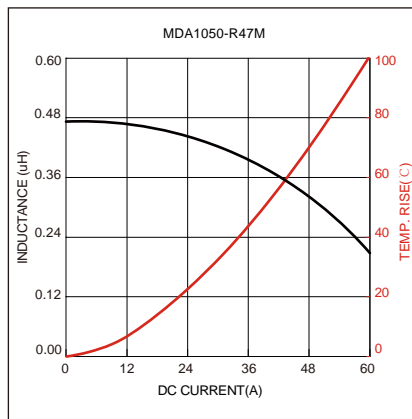
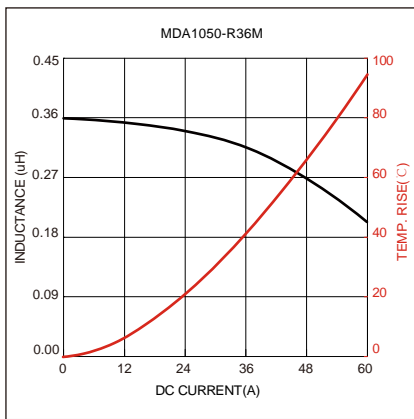


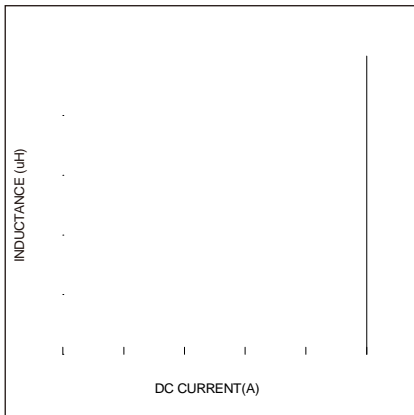
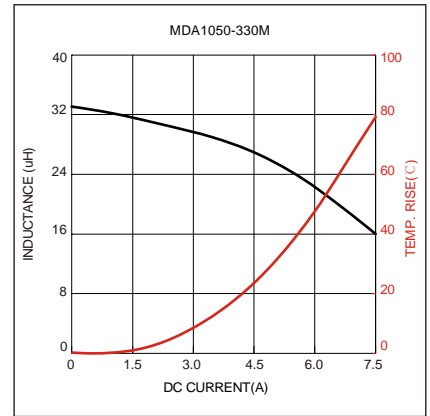
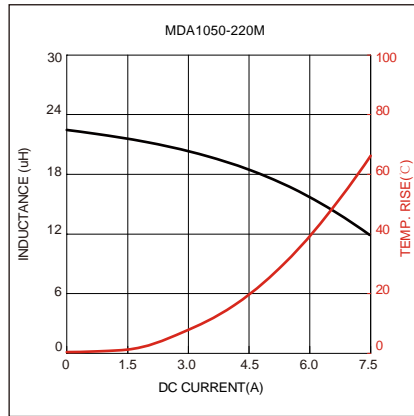
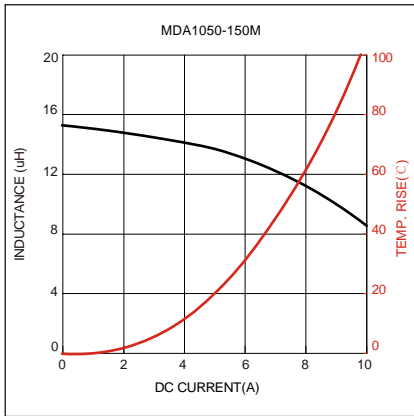
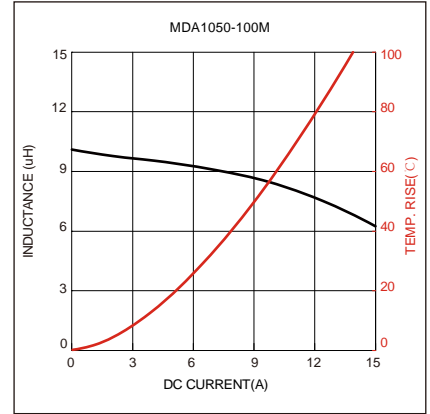
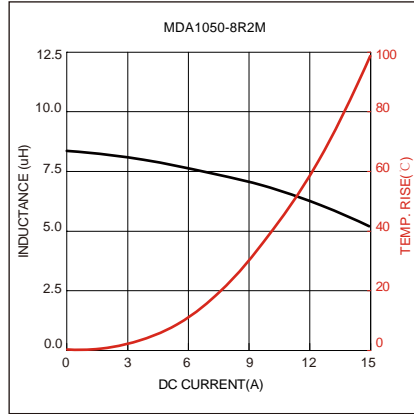
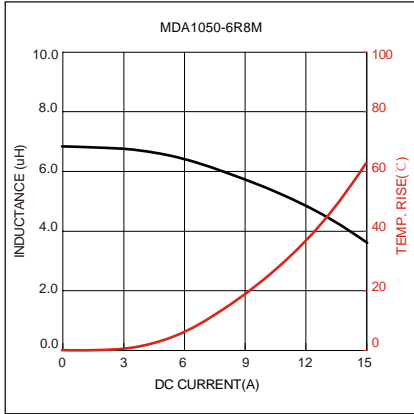
**MDA Series**  
SMD Low Profile High Current Molded Inductor  
Size 1050



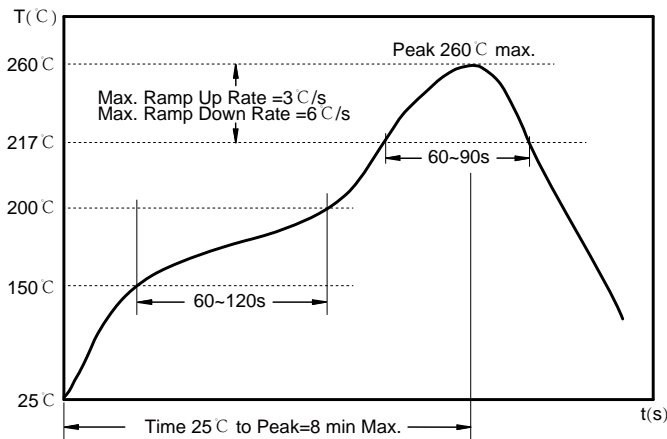
Part No	Inductance @ 100KHz/1V	Tolerance	Temperature Rise Current Typ. (A)	Current Typ. (A)	DC Resistance Typ.	DC Resistance Max.	E
MDA1050-330M	33.0	±20%	5.5	5.8	74.0	86.0	3.0±0.3
MDA1050-470M	47.0	±20%	4.5	4.0	106	127	3.0±0.3

### Typical Electrical Characteristics:





## Soldering Reflow:



Preheat condition: 150 ~200°C / 60~120 sec.

Allowed time above 217°C : 60~90 sec.

Max temperature: 260°C .

Max time at max temperature: 10 sec.

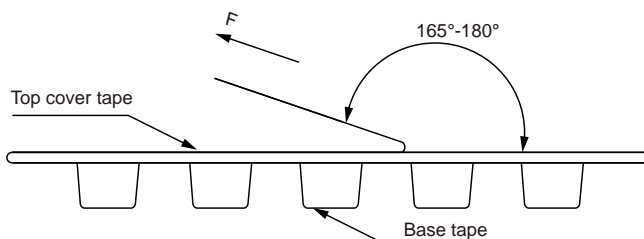
Allowed Reflow time: 2x max.

## Packaging Information:

Tape Dimension :

Series	A0 (mm)	B0 (mm)
MDA1050	10.4± 0.1	

Peel force of top cover tape:

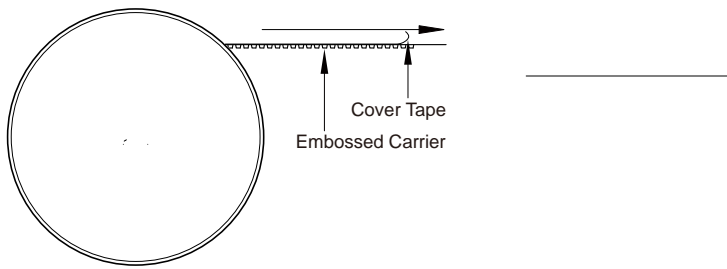


The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

Marking	KH+Printing Inductance+period)

Reel Dimension: [mm]



Packaging Quantity: